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RENESAS TECHNICAL UPDATE

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Product Category	MPU/MCU		Document No.	TN-RZ*-A007A/E	Rev.	1.00
Title	RZ/A1H Group, RZ/A1M Group: Notice of package interposer change of 324-pin BGA package		Information Category	Technical Notification		
Applicable Product	See following	Lot No. All	Reference Document	See following		

In RZ/A1H Group and RZ/A1M Group, package interposer of 324-pin BGA package will be changed in order to improve heat resistance.

Applicable products and relevant documents

Applicable products		Relevant documents	Rev.	Document number
Series	Group			
RZ/A	RZ/A1H RZ/A1M	RZ/A1H Group, RZ/A1M Group User's Manual: Hardware	Rev 2.00	R01UH0403EJ0200

1. The effect of package interposer change

There is no effect on electrical characteristics and reliability by package interposer change. Pin assignment and solder ball coordinate are not changed neither.

However, there is a difference in appearance as described in "2. Detail of change". Please note difference in appearance when execute a visual inspection.

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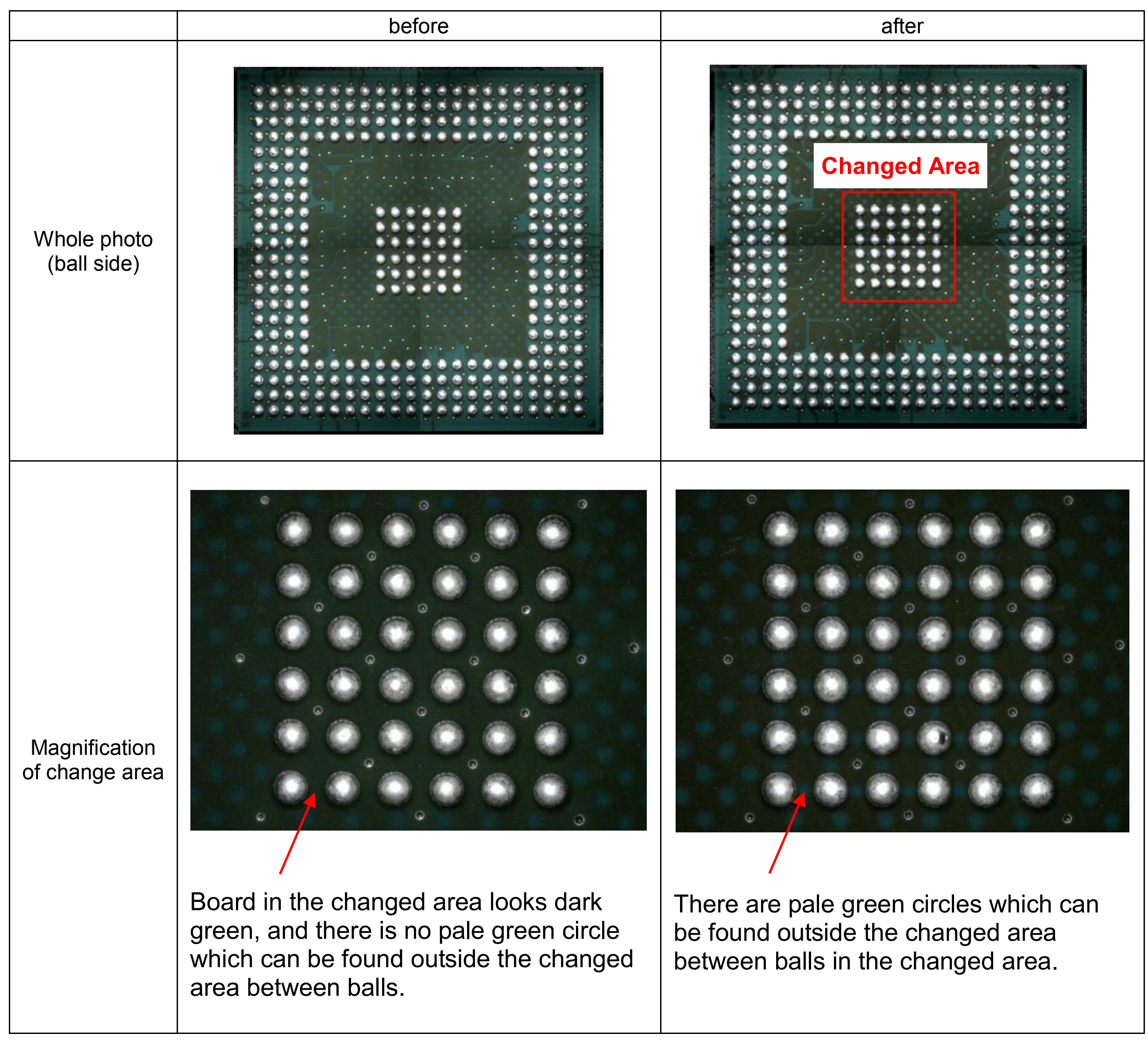
2. Detail of change

Minor modification in the change area of 4th layer (most ball side) of 4 layer board is done.



	before	after
Whole photo (ball side)		
Magnification of change area	Board in the changed area looks dark green, and there is no pale green circle which can be found outside the changed area between balls.	There are pale green circles which can be found outside the changed area between balls in the changed area.

End of document